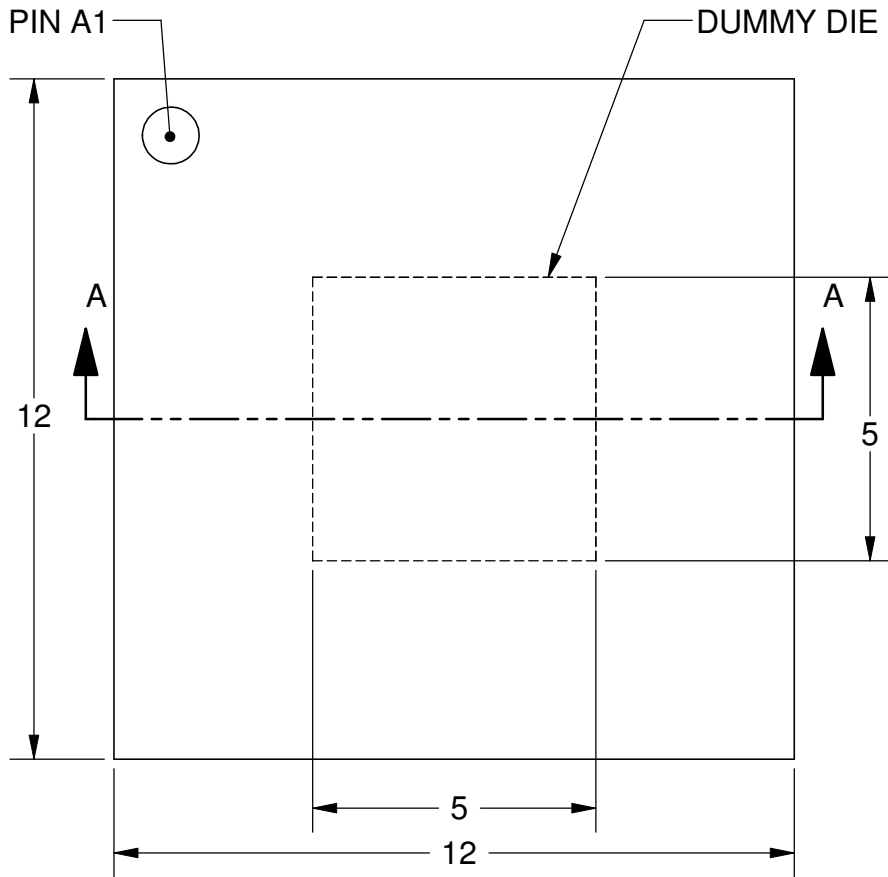
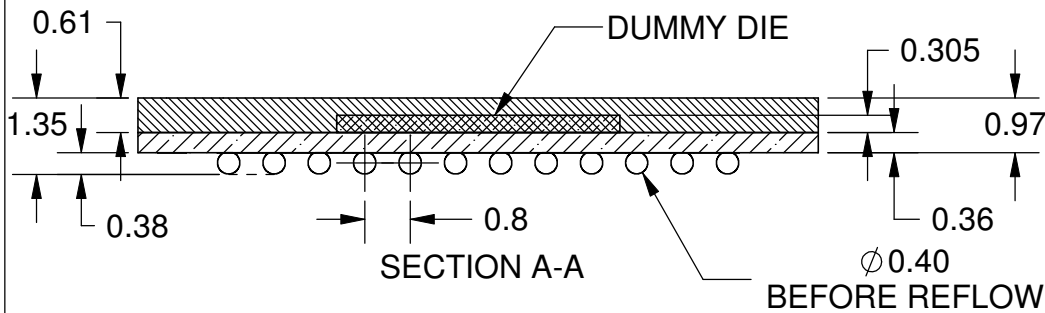
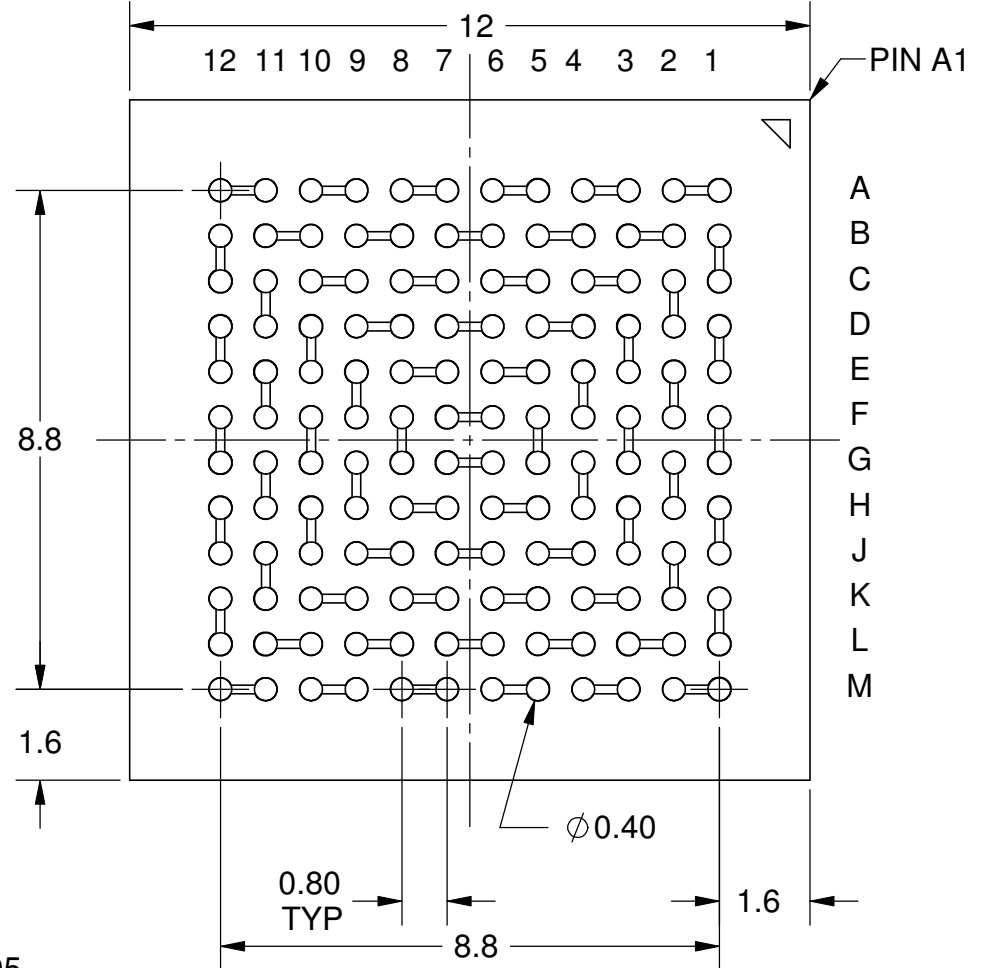


TOP VIEW




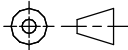
BALL VIEW

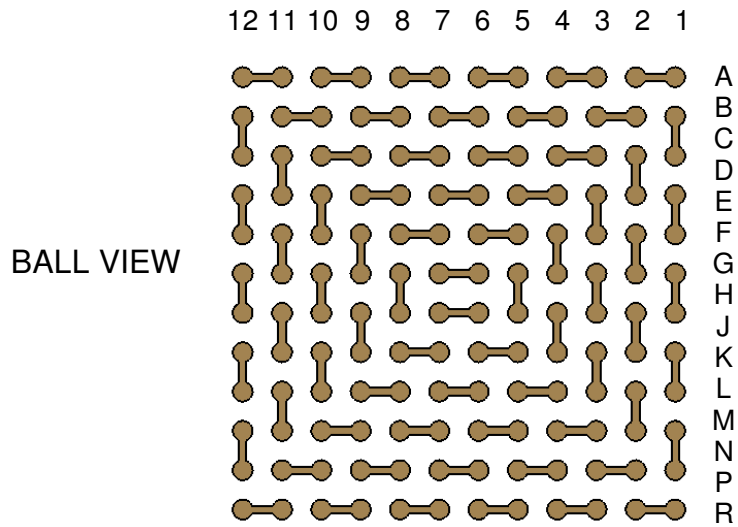


Notes: (Unless Otherwise Specified).

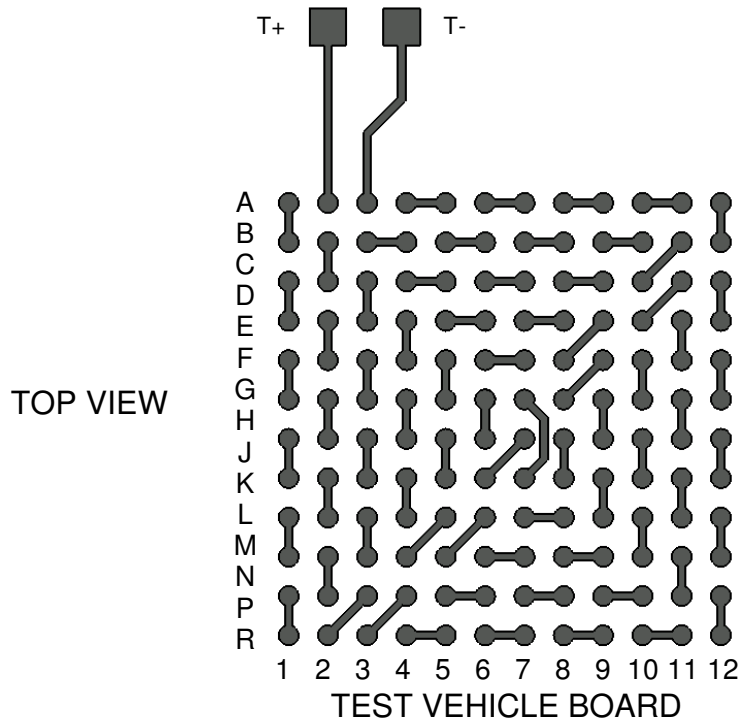
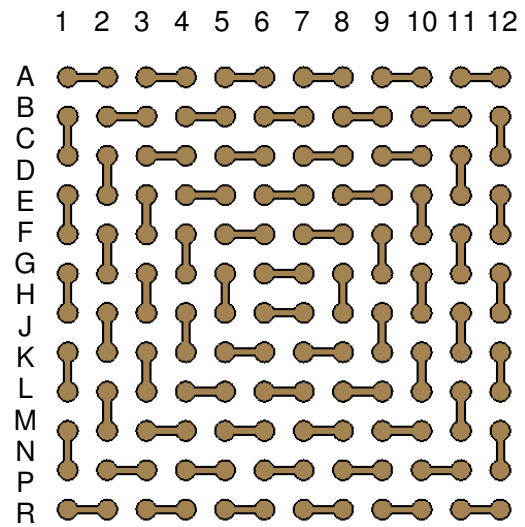
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.32mm (13 mil).
- 5) PAD Cu DIAMETER: 0.406mm (16 mil).
- 6) SUBSTRATE MATERIAL: FR4.
- 7) DUMMY DIE: 0.305mm (12 mil) THICK.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA144T.8C-DC128	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA144T.8C-DC128D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA144T.8-DC128	Sn63/Pb37	NO	NO	NO
BGA144T.8-DC128D	Sn63/Pb37	NO	NO	YES

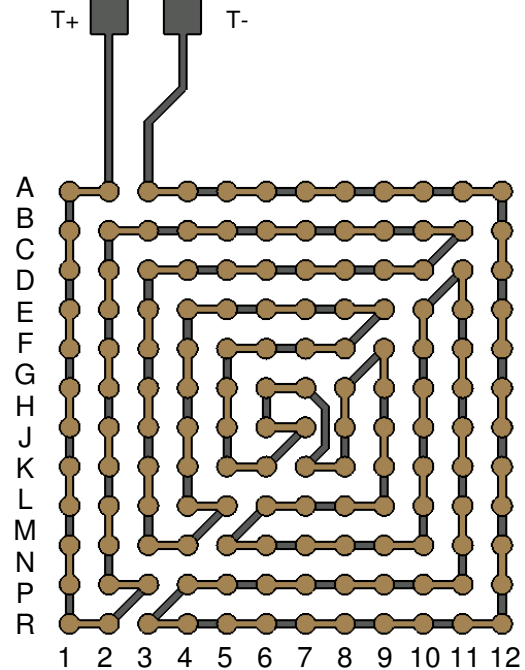
TOLERANCE UNLESS NOTED		APPROVALS		DATE						
X.X	+/- 0.1	DRAWN J. Hines		5/25/2011						TITLE
X.XX	+/- 0.05	ENG				BGA144T.8C-DC128D				
X.XXX	+/- 0.025	MFG				DAISY CHAIN DUMMY				
ANGLES +/- 0.5°		QA		SCALE		SIZE		DRAWING NO.		REV
ALL DIMENSIONS IN		CUST		7.5:1		A		581283		A
INCHES <input type="checkbox"/> MILLIMETERS <input checked="" type="checkbox"/>		REVISED				DO NOT SCALE DRAWING		SHEET 1 OF 2		
THIRD ANGLE PROJECTION										



BOTTOM SIDE  
(TOP X-RAY VIEW)



AFTER MOUNTING  
TO TEST BOARD  
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.406mm (16mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.320mm (13mil).

<b>TopLine</b> ®			
TITLE		BGA144T.8C-DC128D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
6.5:1	A	581283	A
DO NOT SCALE DRAWING			SHEET 2 OF 2